

**DECLARATION AND POWER OF ATTORNEY**

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name; that

I verily believe I am the original, first and sole inventor (if only one name is listed below) or a joint inventor (if plural inventors are named below) of the invention entitled:

**LEAD-FREE SOLDER ALLOY,**

described and claimed

  X   in the attached specification;  
       in the specification filed \_\_\_\_\_,  
 as U.S. Application Serial No. \_\_\_\_\_,  
 and as amended \_\_\_\_\_.

I hereby state that I have reviewed and understand the contents of the above identified specification, including the claims as filed and as amended by any amendment referred to above.

I acknowledge the duty to disclose information which is material to the examination of this application in accordance with Title 37, Code of Federal Regulations, §1.56(a).

**PRIORITY CLAIM**

I hereby claim foreign priority benefits under title 35, United States Code, §119(a)-(d) of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application(s) for patent or inventor's certificate having a filing date before that of the application on which priority is claimed.

Prior Foreign Applications(s)			Priority Claimed	
<u>10-324482</u> (number)	<u>Japan</u> (Country)	<u>28/10/98</u> Day/Mo/Yr	<u>  X  </u> Yes	<u>      </u> No
<u>10-324483</u> (number)	<u>Japan</u> (Country)	<u>28/10/98</u> Day/Mo/Yr	<u>  X  </u> Yes	<u>      </u> No
<u>10-100141</u> (number)	<u>Japan</u> (Country)	<u>26/03/98</u> Day/Mo/Yr	<u>  X  </u> Yes	<u>      </u> No

SECRET 250515Z

I hereby claim the benefit under Title 35, United States Code, §119(e) of any United States provisional application(s) listed below.

Application No.

Filing Date

Application No.

Filing Date

I hereby claim the benefit under Title 35, United States Code, §120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code, §112, I acknowledge the duty to disclose material information as defined in Title 37, Code of Federal Regulations, §1.56(a) which occurred between the filing date of the prior application and the national or PCT international filing date of this application:

Application Serial No.

Filing Date

Status

Application Serial No.

Filing Date

Status

I appoint

Theodore D. Lienesch	Reg. No. 28,235
Mark P. Levy	Reg. No. 27,922
J. Daniel Lykins	Reg. No. 27,354
David A. Mancino	Reg. No. 39,289
Michael J. Nieberding	Reg. No. 39,316
Steven J. Elleman	Reg. No. 41,733
John M. Mueller	Reg. No. 44,248
John F. Kane	Reg. No. 44,815

my attorneys with full power of substitution and revocation, to prosecute this application and to transact all business in the Patent and Trademark Office connected therewith. Address all telephone calls to (937) 443-6958. Address all correspondence to: Thompson Hine & Flory LLP, 2000 Courthouse Plaza N.E., P.O. Box 8801, Dayton, Ohio 45401-8801, Attention: Theodore D. Lienesch.

I further declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under §1001 of Title 18 of the United States Code, and that such willful false statements may

Post Office Address: c/o Nihon Superior Sha Co., Ltd.  
16-15 Esakacho 1-chome  
Suita-shi Osaka 564-0063

Docket No.: 550718-00070

Applicant or Patentee : Nishimura Tetsuro  
Filed or Issued : Herewith  
For : LEAD-FREE SOLDER ALLOY

**VERIFIED STATEMENT (DECLARATION) CLAIMING SMALL ENTITY STATUS  
(37 CFR 1.9(f) and 1.27(c)) - SMALL BUSINESS CONCERN**

I declare that I am

- ☐ the owner of the small business concern identified below:  
☒ an official of the small business concern empowered to act on behalf of  
the concern identified below:

NAME OF CONCERN: Nihon Superior Sha Co., Ltd.  
ADDRESS OF CONCERN: 16-15 Esakacho 1-chome, Suita-shi Osaka 564-0063 JAPAN

I hereby declare that the above identified small business concern qualifies as a small business concern as defined in 13 CFR 121.3-18, and reproduced in 37 CFR 1.9(d), for purposes of paying reduced fees under section 41(a) and (b) of Title 35, United States Code, in that the number of employees of the concern, including those of its affiliates, does not exceed 500 persons. For purposes of this statement, (1) the number of employees of the business concern is the average over the previous fiscal year of the concern of the persons employed on a full-time, part-time or temporary basis during each of the pay periods of the fiscal year, and (2) concerns are affiliates of each other when either, directly or indirectly, one concern controls or has the power to control the other, or a third party or parties controls or has the power to control both.

I hereby declare that rights under contract or law have been conveyed to and remain with the small business concern identified above with respect to the invention, entitled LEAD-FREE SOLDER ALLOY by inventor(s) Nishimura Tetsuro, described in

- ☒ the specification filed herewith  
☐ Application Serial No. \_\_\_\_\_, filed \_\_\_\_\_  
☐ Patent No. \_\_\_\_\_, issued \_\_\_\_\_

If the rights held by the above identified small business concern are not exclusive, each individual, concern or organization having rights to the invention is listed below\* and no rights to the invention are held by any person, other than the inventor, who could not qualify as a small business concern under 37 CFR 1.9(d) or by any concern which would not qualify as a

small business concern under 37 CFR 1.9(d) or a nonprofit organization under 37 CFR 1.9(e).  
\*NOTE: Separate verified statements are required from each named person, concern or organization having rights to the invention averring to their status as small entities. (37 CFR 1.27)

NAME \_\_\_\_\_

ADDRESS \_\_\_\_\_

[ ]INDIVIDUAL [X] SMALL BUSINESS CONCERN [ ]NONPROFIT ORGANIZATION

I acknowledge the duty to file, in this application or patent, notification of any change in status resulting in loss of entitlement to small entity status prior to paying, or at the time of paying, the earliest of the issue fee or any maintenance fee due after the date on which status as a small entity is no longer appropriate. (37 CFR 1.28(b))

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under §1001 of Title 18 of the United States Code, and that such willful false statements may jeopardize the validity of the application, any patent issuing thereon, or any patent to which this verified statement is directed.

NAME OF PERSON SIGNING:

Nishimura Tetsuro

TITLE OF PERSON OTHER THAN OWNER:

ADDRESS OF PERSON SIGNING:

c/o Nihon Superior Sha Co., Ltd.  
16-15, Esakacho 1-chome  
Suita-shi Osaka 564-0063  
JAPAN

SIGNATURE \_\_\_\_\_

DATE: \_\_\_\_\_